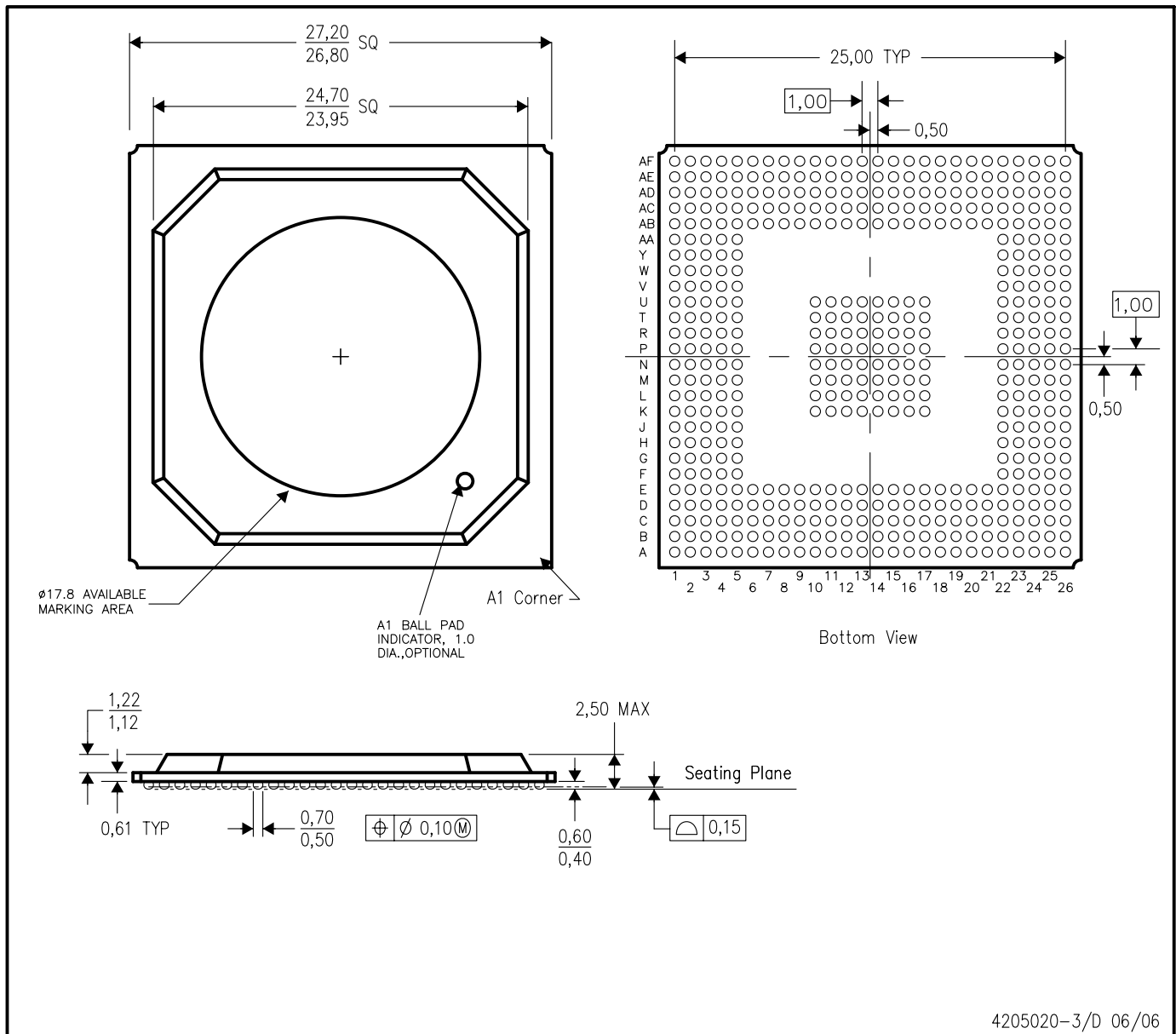


ZED (S-PBGA-N484)

PLASTIC BALL GRID ARRAY



4205020-3/D 06/06

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. This drawing conforms to the JEDEC registered outline MS-034/A variation AAL-1.
 - D. This is a lead-free solder ball design.

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